TECHNICAL DATA SHEET

Armstrong A-706

Issue date: 12/8/2021

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
1-877-259-1669

DESCRIPTION:

ResinLab®Armstrong™ A-706 is a one-part heat cure epoxy system. A latent catalyst initiates the reaction at temperatures of 120 °C or greater.

Armstrong™ A-706 contains metallic aluminum fillers that impart excellent room temperature tensile strength and machining properties. This product is not recommended for applications requiring electrical resistance.

Armstrong™ A-706 can be certified to the following Military Specifications:

MMM-A134, Type III

TYPICAL PROPERTIES:

All properties given are at 25 °C unless otherwise noted.

Property:	*Value:*	*Test Method or Source:*
Color	Gray Aluminum	
Cure Schedule	2 hours @ 177 °C	Extrapolated from Henkel LDS
Viscosity	124,000 cP	Rheometer parallel plate 25mm @ 1/s 455300006291
Specific Gravity	1.55	Calculated
Work Life	Indefinite @ 25 °C, evaluated at 100 g and 1 lb mass	Extrapolated from Henkel LDS
Hardness	80 Shore D	455300006287/ASTM D2240
Lap Shear Strength **0.005" Bond Line, Al to Al**	4,620 psi @ 23 °C 4,330 psi after 30 min @ 85 °C 4,630 psi after 60 min @ 71 °C + 30 min @ -55 °C 4,120 psi after 250 hr salt spray exposure 4,300 psi after 30 min @ -55 °C 4,640 psi after 7 days in distilled water 3,920 psi after 168 hours accelerated weathering 4,460 psi after 7 days in anti-icing fluid 4,760 psi after 7 days in hydraulic oil 4,800 psi after 7 days in JP4 4,480 psi after 7 days in hydrocarbon fluid	Extrapolated from Henkel LDS
Cleavage Strength	4,310 lb	Extrapolated from Henkel LDS
Creep-Rupture Strength	> 1,600 psi tested at @ 23 ± 1 °C > 300 psi tested at @ 82 ± 1 °C	Extrapolated from Henkel LDS

TECHNICAL DATA SHEET

Armstrong A-706

Issue date: 12/8/2021

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
1-877-259-1669

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.
** Operating Temperature Range is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.
*** This TDS contains values that have been updated. The values reported in this technical data sheet are typical values of the product, and are highly dependent on test conditions and methodology. We actively seek the most precise and accurate ways to measure and interpret performance of our products, and to update estimated values with measured values. The formula has not been revised or changed in any way. Although the values on paper have changed, you can expect the same performance of the product.

INSTRUCTIONS:

1. Bring to room temperature prior to use.
2. Stir before using, avoid the introduction of exess air.
3. Apply a thin layer (3-5mils) of adhesive evenly on the bonding surface and press together gently. Contact pressure or light clamping will hold parts in place during cure. Apply heat to cure.
4. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
5. Clean up uncured resin with suitable organic solvent such as MEK or acetone.

SHELF LIFE AND STORAGE:

9 months DOP at 5 °C.
Specialty packaging may be less.
Usable shelf life is dependent upon method of application, storage conditions and user requirements.

NOTE: This product is sensitive to excursions above room temperature. Exposure to higher temperature, or cycling of product temperature, will shorten product shelf life.